

**GALLIUM NITRIDE BASED CIRCUITS FOR  
MICROWAVE SIGNAL GENERATION**

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MICROWAVE SIGNAL GENERATION**

*by*

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**Submitted**

**in fulfilment of the requirements of the degree of Doctor of Philosophy  
to the**



**INDIAN INSTITUTE OF TECHNOLOGY DELHI**

**JULY 2022**



**To**  
**MY FAMILY**



## **CERTIFICATE**

This is to certify that the work reported in this thesis entitled “**Gallium Nitride Based Circuits for Microwave Signal Generation**” being submitted by **Ms. Rakhi Kumari** for the award of the degree of **Doctor of Philosophy** to the Indian Institute of Technology Delhi, New Delhi, India, is a record of original bonafide research work carried out by her under our guidance and supervision. The results contained in this thesis have not been submitted in part or full, to any other university or institute for the award of any degree or diploma.

We certify that she has pursued the prescribed course of research.

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## ABSTRACT

The major limitations of high range and high-resolution radar at microwave and millimeter wave frequency is the unavailability of compact, efficient high-power source with low distortion using solid state devices. The Current most promising solid-state technology for high power handling is GaN/AlGaN based high electron mobility transistors (HEMT) at microwave and millimeter wave frequency. A key advantage to GaN is its ability to maintain high operating voltage at higher frequency range. This is due to the unique combination of high band gap energy resulting in higher device tolerance for high field strengths, as well as the high-speed properties of electron mobility and saturation velocity due to hetro-structure at junction and polarization effect. Due to high mobility and high saturation velocity these transistors can be operated at microwave and millimeter wave frequency. These devices can handle high voltage due to the wide band-gap of GaN and have high carrier density due to polarization effects and structure of HEMT. Hence these devices have high power handling and high-power generating capacity with less distortion at microwave and millimeter wave frequency range.

This thesis work is focused on developing GaN/AlGaN HEMT based High power sources using active integrated antenna (AIA) approach. One goal of this thesis is to develop a high-power amplifier type AIA. While most reports on GaN HEMT concentrate on power amplifiers, this design also combines AIA approach with power amplifier design to make the system compact and increase effective isotropic radiated power (EIRP). The measured EIRP of this circuit is 49 dBm. Which is better than the state-of-the-art results reported for GaN HEMT based active integrated antenna.

The second goal of this thesis is to develop GaN/AlGaN HEMT based self-oscillating AIA. This oscillator design is based on negative impedance technique and AIA approach. Here the patch antenna is connected at the output side of the oscillator and performs multiple functions and makes the system compact. It acts like a load, resonator and radiator. The two circuits using the same approach are developed using a single device. The measured EIRP of the first circuit is 18 dBm power at 1.5 GHz. The measured EIRP of the second circuit is 29 dBm at 2 GHz frequency.

The third goal of this thesis is to develop GaN/AlGaN HEMT based self-oscillating AIA, where the AIA approach is used to maximize the radiated power at second harmonic. Hence the frequency of power generation is doubled. Two circuits are designed for this purpose. The measured EIRP of the first circuit is 32 dBm at second harmonic (3 GHz) and 16 dBm at fundamental frequency (1.5 GHz). In the second circuit the negative impedance region (frequency) is increased using a coupled line in parallel with the device, the AIA approach is also used to maximize the radiated power at second harmonic. So, this circuit generates high power at higher frequency. In simulation this circuit has simulated power of 37 dBm at second harmonic of 8 GHz and 20 dBm at fundamental frequency (4 GHz). So, the proposed GaN HEMT based AIA concept can be used to generate useful power at higher frequency and this technique will be very useful in extending the frequency of operation of circuit beyond the operating frequency range of transistors used in the circuit.

The final goal of this circuit is to develop GaN/AlGaN HEMT based self-oscillating fixed frequency and frequency reconfigurable AIA high power source using feedback topology. The fixed frequency circuit implemented radiates 41 dBm power at 2.4 GHz, which is the highest EIRP using a single device. In frequency reconfigurable AIA, the frequency of oscillation changes from 2.1 GHz to 2.7GHz, when pin diodes change its state from off state to on state. The second circuit has EIRP within 1dB in both states. This circuit is very compact and can generate two frequencies by changing the biasing of pin diodes without changing the circuit footprint. This circuit is the first implementation of GaN/AlGaN HEMT based reconfigurable oscillating AIA.

Due to the above-mentioned design concept and approaches on design level, this work provides the basis for the design and implementation of GaN/AlGaN HEMT based high power sources at microwave and millimeter wave frequency. Also, the power can be further increased using spatial power combining technique. Therefore, GaN/AlGaN based high power circuits are of great interest for long range solid-state phased-array systems.

## सारांश

माइक्रोवेव और मिलीमीटर तरंग आवृत्ति पर अधिक रेंज और अधिक रिज़ॉल्यूशन रडार की प्रमुख सीमाएं ठोस अवस्था उपकरणों का उपयोग करके कम विरूपण के साथ कॉम्पैक्ट, कुशल, अधिक शक्ति स्रोत की अनुपलब्धता है। अधिक शक्ति हैंडलिंग के लिए वर्तमान में सबसे आशाजनक ठोस अवस्था तकनीक माइक्रोवेव और मिलीमीटर तरंग आवृत्ति पर GaN / AlGaN आधारित अधिक इलेक्ट्रॉन गतिशीलता ट्रांजिस्टर (HEMT) है। GaN के लिए एक महत्वपूर्ण लाभ अधिक आवृत्ति सीमा पर अधिक ऑपरेटिंग वोल्टेज बनाए रखने की इसकी क्षमता है। यह अधिक बैंड गैप ऊर्जा के अद्वितीय संयोजन के कारण होता है जिसके परिणामस्वरूप अधिक विद्युत क्षेत्र की ताकत के लिए अधिक उपकरण सहिष्णुता होती है, साथ ही जंक्शन और ध्रुवीकरण प्रभाव पर हेट्रो-संरचना के कारण इलेक्ट्रॉन गतिशीलता और संतृप्ति वेग के अधिक गति के गुण होते हैं। अधिक गतिशीलता और अधिक संतृप्ति वेग के कारण इन ट्रांजिस्टर को माइक्रोवेव और मिलीमीटर तरंग आवृत्ति पर संचालित किया जा सकता है। ये उपकरण GaN के व्यापक बैंड-गैप के कारण अधिक वोल्टेज को संभाल सकते हैं और ध्रुवीकरण प्रभाव और HEMT की संरचना के कारण अधिक वाहक घनत्व है। इसलिए इन उपकरणों में माइक्रोवेव और मिलीमीटर तरंग आवृत्ति सीमा पर कम विरूपण के साथ अधिक शक्ति हैंडलिंग और अधिक शक्ति उत्पादन क्षमता होती है।

यह थीसिस काम सक्रिय एकीकृत एंटीना (AIA) तकनीक का उपयोग करके GaN / AlGaN HEMT आधारित अधिक शक्ति स्रोतों को विकसित करने पर केंद्रित है। इस थीसिस का एक लक्ष्य एक अधिक शक्ति एम्पलीफायर प्रकार का AIA विकसित करना है। जबकि GaN HEMT पर अधिकांश रिपोर्टें पावर एम्पलीफायरों पर ध्यान केंद्रित करती हैं, यह डिज़ाइन सिस्टम को कॉम्पैक्ट बनाने और प्रभावी आइसोट्रोपिक विकीर्ण शक्ति (EIRP) को बढ़ाने के लिए पावर एम्पलीफायर डिज़ाइन के साथ AIA तकनीक को भी जोड़ती है। इस परिपथ का मापा गया EIRP 49 dBm है। जो GaN HEMT आधारित AIA के लिए रिपोर्ट किए गए अत्याधुनिक परिणामों से बेहतर है।

इस थीसिस का दूसरा लक्ष्य GaN / AlGaN HEMT आधारित स्व-दोलन AIA विकसित करना है। यह दोलन डिज़ाइन नकारात्मक प्रतिबाधा तकनीक और एआईए दृष्टिकोण पर आधारित है। यहां पैच एंटीना दोलन के आउटपुट पक्ष पर जुड़ा हुआ है और कई कार्य करता है और सिस्टम कॉम्पैक्ट बनाता है। यह एक लोड, resonator और रेडिएटर की तरह कार्य करता है। एक ही तकनीक और एक ही

डिवाइस का उपयोग करके दो सर्किट विकसित किए गए हैं। पहले परिपथ का मापा गया EIRP 1.5 GHz पर 18 dBm शक्ति है। दूसरे परिपथ का मापा गया EIRP 2 गीगाहर्ट्ज आवृत्ति पर 29 dBm है।

इस थीसिस का तीसरा लक्ष्य GaN / AlGaN HEMT आधारित स्व-दोलन AIA विकसित करना है, जहां AIA तकनीक का उपयोग दूसरे हार्मोनिक पर विकीर्ण शक्ति को अधिकतम करने के लिए किया जाता है। इसलिए विद्युत उत्पादन की आवृत्ति दोगुनी हो जाती है। इस उद्देश्य के लिए दो सर्किट डिज़ाइन किए गए हैं। पहले परिपथ का मापा गया EIRP दूसरे हार्मोनिक (3 GHz) पर 32 dBm और मौलिक आवृत्ति (1.5 GHz) पर 16 dBm है। दूसरे सर्किट में नकारात्मक प्रतिबाधा क्षेत्र (आवृत्ति) डिवाइस के साथ समानांतर में एक युग्मित रेखा का उपयोग करके बढ़ाया जाता है, एआईए तकनीक का उपयोग दूसरे हार्मोनिक पर विकीर्ण शक्ति को अधिकतम करने के लिए भी किया जाता है। इसलिए, यह सर्किट अधिक आवृत्ति पर अधिक शक्ति उत्पन्न करता है। सिमुलेशन में इस सर्किट में 8 गीगाहर्ट्ज, दूसरे हार्मोनिक पर 37 डीबीएम की शक्ति है और मौलिक आवृत्ति (4 गीगाहर्ट्ज) पर 20 डीबीएम है। इसलिए, प्रस्तावित GaN HEMT आधारित AIA तकनीक का उपयोग अधिक आवृत्ति पर उपयोगी शक्ति उत्पन्न करने के लिए किया जा सकता है और यह तकनीक सर्किट में उपयोग किए जाने वाले ट्रांजिस्टर की ऑपरेटिंग आवृत्ति सीमा से परे सर्किट के संचालन की आवृत्ति का विस्तार करने में बहुत उपयोगी होगी।

इस सर्किट का अंतिम लक्ष्य GaN / AlGaN HEMT आधारित स्व-दोलन निश्चित आवृत्ति और आवृत्ति reconfigurable AIA अधिक शक्ति स्रोत प्रतिक्रिया टोपोलॉजी का उपयोग कर विकसित करने के लिए है। कार्यान्वित किया गया निश्चित आवृत्ति सर्किट 2.4 गीगाहर्ट्ज पर 41 डीबीएम पावर विकीर्ण करता है, जो एक एकल डिवाइस का उपयोग करके उच्चतम ईआईआरपी है। आवृत्ति Re-configuration एआईए में, दोलन की आवृत्ति 2.1 गीगाहर्ट्ज से 2.7 गीगाहर्ट्ज में बदल जाती है, जब पिन डायोड अपनी स्थिति को ऑफ अवस्था से on अवस्था पर बदल देते हैं। दूसरे सर्किट में दोनों अवस्था में 1dB के भीतर EIRP है। यह सर्किट बहुत कॉम्पैक्ट है और सर्किट पदचिह्न को बदलने के बिना पिन डायोड के बायसिंग को बदलकर दो आवृत्तियों को उत्पन्न कर सकता है। यह परिपथ GaN/AlGaN HEMT आधारित आवृत्ति Re-configuration करने योग्य दोलन AIA का पहला कार्यान्वयन है।

डिजाइन स्तर पर उपर्युक्त डिजाइन अवधारणा और दृष्टिकोण के कारण, यह काम माइक्रोवेव और मिलीमीटर तरंग आवृत्ति पर GaN / AlGaN HEMT आधारित अधिक शक्ति स्रोतों के डिजाइन और कार्यान्वयन के लिए आधार प्रदान करता है। इसके अलावा, spatial power combining तकनीक

का उपयोग करके शक्ति को और बढ़ाया जा सकता है। इसलिए, GaN / AlGaN आधारित उच्च शक्ति सर्किट लंबी दूरी के ठोस अवस्था phased-array systems के लिए बहुत महत्वपूर्ण हैं।



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## LIST OF ABBREVIATIONS

<b>ADS</b>	Design System
<b>AESA</b>	Active Electronically Scanned Array
<b>AIA</b>	Active Integrated Antenna
<b>AlGaN</b>	Aluminium Gallium Nitrid
<b>BSF</b>	Band Stop Filter
<b>COAs</b>	Coupled Oscillator Arrays
<b>CST</b>	Computer Simulation Technology
<b>CW</b>	Continuous Wave
<b>dB</b>	Decibel
<b>dBc</b>	Decibel reference to Carrier
<b>dBm</b>	Decibel reference to 1 mW
<b>DC</b>	Direct Current
<b>DSRC</b>	Dedicated short-range communication
<b>EIRP</b>	Effective Isotropic Radiated Power
<b>EM</b>	Electromagnetic
<b>EV</b>	Electric Vehicle
<b>FOV</b>	Field of view
<b>GaAs</b>	Gallium Arsenide
<b>GaN</b>	Gallium Nitride
<b>GHz</b>	Giga Hertz
<b>GPS</b>	Global Positioning System
<b>HBT</b>	Hetero-junction Bipolar Transistor
<b>HJFET</b>	Hetero-Junction Field Effect Transistor
<b>HEMT</b>	High Electron Mobility Transistor
<b>HF</b>	High Frequency

<b>Hz</b>	Hertz
<b>IME</b>	Impedance Mismatch Efficiency
<b>IEEE</b>	Institute of Electrical and Electronics Engineering
<b>IMN</b>	Input Matching Network
<b>IMPATT</b>	IMPact ionization Avalanche Transit-Time diode
<b>InGaP</b>	Indium Gallium Phosphide
<b>LDMOS</b>	lateral-diffused metal–oxide–semiconductors
<b>LFN</b>	Low frequency noise
<b>MAG</b>	Maximum Available Gain
<b>MEMS</b>	Micro-electromechanical systems
<b>μF</b>	Micro Farad
<b>MHz</b>	Mega Hertz
<b>MIC</b>	Microwave Integrated Circuit
<b>MMIC</b>	Microwave Integrated Circuit
<b>MPT</b>	Microwave Power Transmission
<b>mW</b>	Milli Watt
<b>nH</b>	Nano Henry
<b>OMN</b>	Onput Matching Network
<b>PA</b>	power Amplifier
<b>PAE</b>	Power Added Efficiency
<b>PCB</b>	Printed Circuit Board
<b>pF</b>	Pico Farad
<b>PIN</b>	P type – Intrinsic – N type
<b>PPM</b>	Parts per million
<b>PSD</b>	power spectral density
<b>Q factor</b>	Quality factor
<b>Q point</b>	Quiescent Point
<b>RADAR</b>	Radio Detection and Ranging
<b>RF</b>	Radio Frequency
<b>RFID</b>	Radio Frequency Identification
<b>SA</b>	Spectrum Analyzer/ Signal Analyzer

<b>SiC</b>	Silicon Carbide
<b>SMA</b>	Sub Miniature version A type
<b>S-Parameter</b>	Scattering Parameter
<b>TL</b>	Transmission Line
<b>TRM</b>	Transmit/Receive Modules
<b>TX</b>	Transmitter
<b>UMTS</b>	Universal Mobile Telecommunications Service
<b>VCO</b>	Voltage Controlled Oscillator
<b>VEDs</b>	Vacuum Electron Devices
<b>VHF</b>	Very High Frequency
<b>VNA</b>	Vector Network Analyzer
<b>WiFi</b>	Wireless Fidelity
<b>WiMAX</b>	Worldwide Interoperability for Microwave Access
<b>WLAN</b>	Wireless Local Area Network
<b>2-DEG</b>	Two-Dimensional Electron Gas
<b>5G</b>	The Fifth Generation of cellular networks

